

BROWN
School of Engineering

DIGITAL ELECTRONICS SYSTEM DESIGN

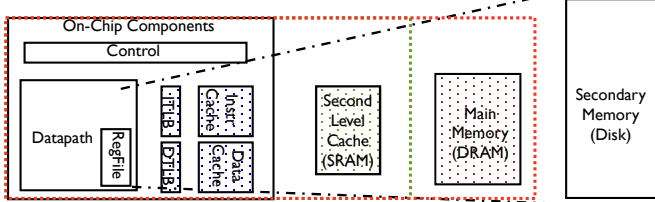
FALL 2019
PROF. IRIS BAHAR
DECEMBER 2, 2019
LECTURE 23: STATIC MEMORY DESIGN

COURSE EVALUATIONS

- Course evaluation forms are now available
- Please access using Banner self service
- Filling out this form provides me with important feedback about your experience with this course.
- Comments are confidential
- Available to me only after grades have been submitted.
- Thanks!

A TYPICAL MEMORY HIERARCHY

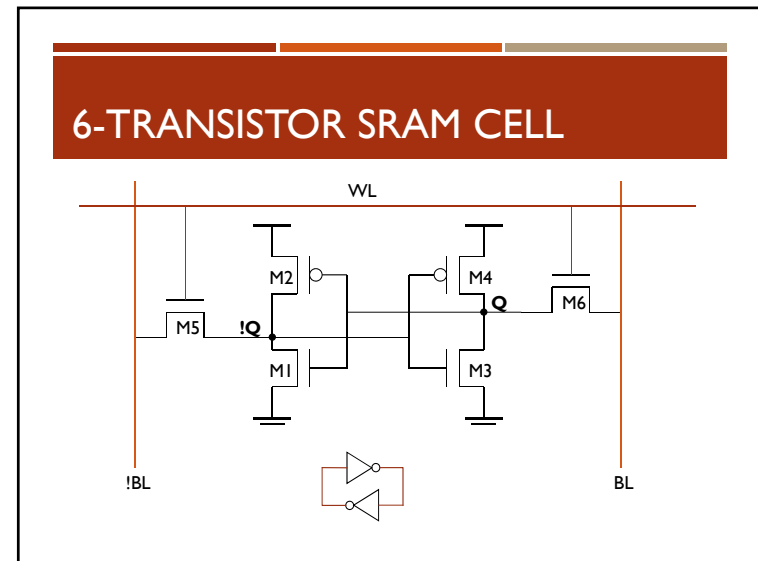
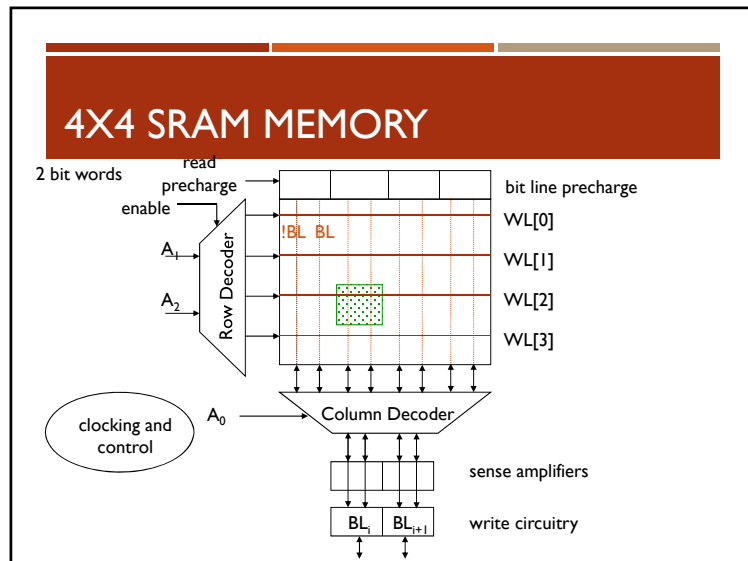
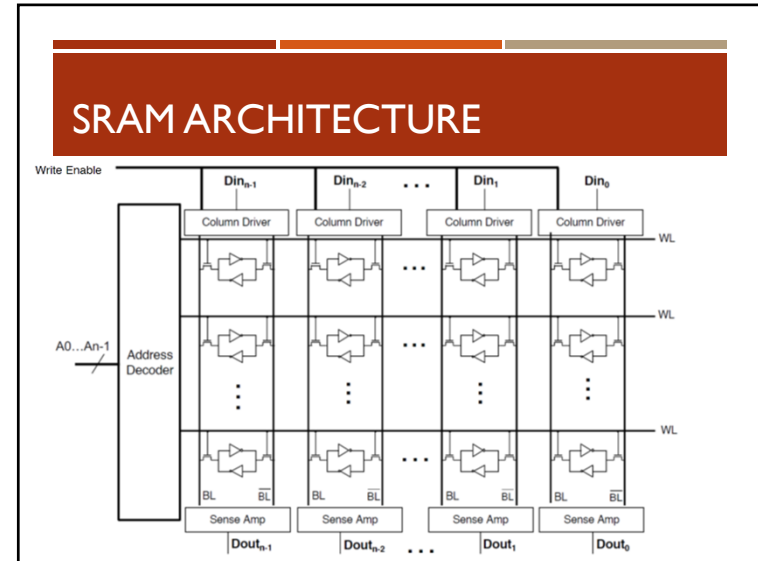
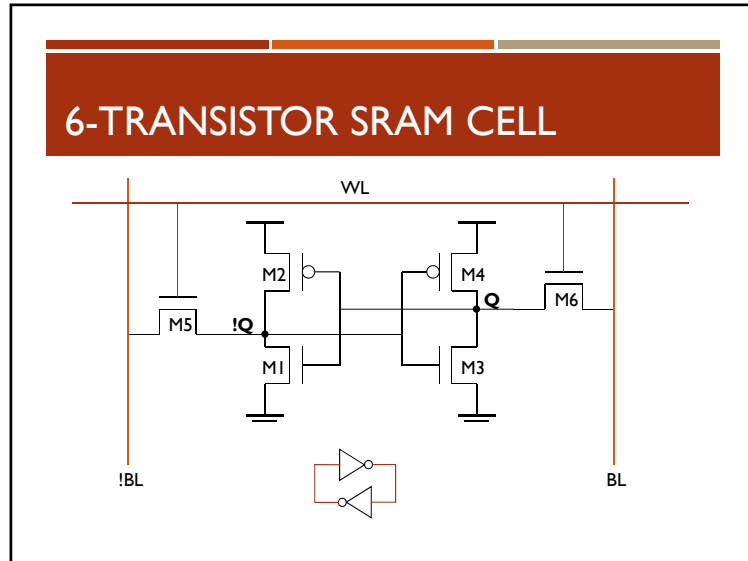
- By taking advantage of the principle of locality, we can:
 - present the user with as much memory as is available in the cheapest technology
 - at the speed offered by the fastest technology.



	On-Chip Components				
	Control				
	Datapath	Register	1T1B Cache	1T1B Cache	
			Instr. Cache	Data Cache	
			Second Level Cache (SRAM)	Main Memory (DRAM)	Secondary Memory (Disk)
Speed (ns):	.1's	1's	10's	100's	1,000's
Size (bytes):	100's	KB's	10KB's	MB's	TB's
Cost:	highest				lowest

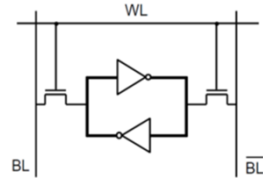
READ/WRITE MEMORIES (RAMS)

- Static – SRAM**
 - data is stored as long as voltage supply is enabled
 - large cells (6 FETs/cell) → fewer bits/chip
 - fast → used where speed is important (e.g., caches)
- Dynamic – DRAM**
 - periodic refresh required (every 1 to 4 ms)
 - small cells (1 to 3 FETs/cell) → more bits/chip
 - slower → used for main memories



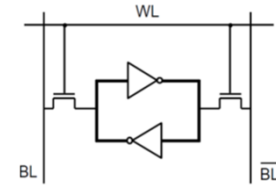
SRAM WRITE

- Drive on bit line high, the other low (depending on the desired write value)
- Then enable the word line (WL)
- Bit lines overpower cell with new value



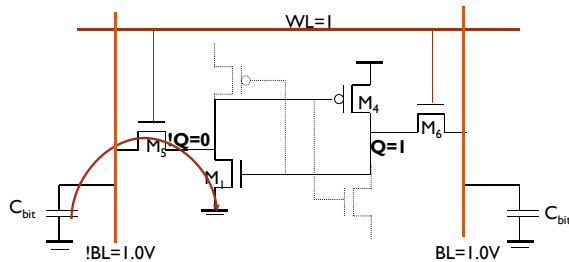
SRAM READ

- Precharge both bit lines high
- Then enable word line (WL)
- One of the two bit lines will be pulled down by the cell
 - Change detected by sensor amplifier



*How does the SRAM distinguish between reading or writing a cell?
How do you make sure you don't accidentally overwrite a cell value when you are trying to read?*

SRAM CELL ANALYSIS (READ)

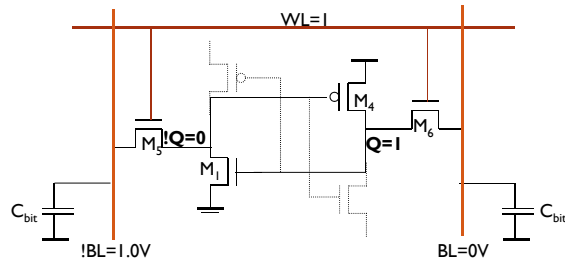


Read-disturb (read-upset): must carefully limit the allowed voltage rise on !Q to a value that prevents the read-upset condition from occurring while simultaneously maintaining acceptable circuit speed and area constraints

READ VOLTAGE RATIOS

- Keep cell size minimal while maintaining read stability
 - Make M_1 minimum size and increase the L of M_5 (to make it weaker)
 - Increases load on BL
 - Make M_5 minimum size and increase the W of M_1

SRAM CELL ANALYSIS (WRITE)



The !Q side of the cell cannot be pulled high enough to ensure writing of 1 (because of the on state of M_1). So, the new value of the cell has to be written through M_6 .

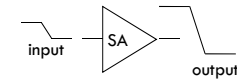
WRITE VOLTAGE RATIOS

- Need to pull Q below V_{thn} to turn off M_1
- Keep cell size minimal while allowing writes
 - Make M_4 and M_6 minimum size
- Be sure to consider worst case process corners

CELL SIZING AND PERFORMANCE

- Keeping cell size minimal is critical for large caches
 - Minimum sized pull down devices (M_1 and M_3)
 - Requires longer than minimum channel length pass transistors (M_5 and M_6) to ensure proper Cell Ratio
 - But up-sizing of the pass transistors increases capacitive load on the word lines and limits the current discharged on the bit lines both of which can adversely affect the speed of the read cycle
 - Minimum width and length pass transistors
 - Boost the width of the pull downs (M_1 and M_3)
 - Reduces the loading on the word lines and increases the storage capacitance in the cell – both are good! – but cell size may be slightly larger
- Performance is determined by the read operation
 - To accelerate the read time, SRAMs use sense amplifiers (so that the bit line doesn't have to make a full swing)

SENSE AMPLIFIERS



- Amplification: resolves data with small bit line swings
- Delay reduction: compensates for the limited drive capability of the memory cell

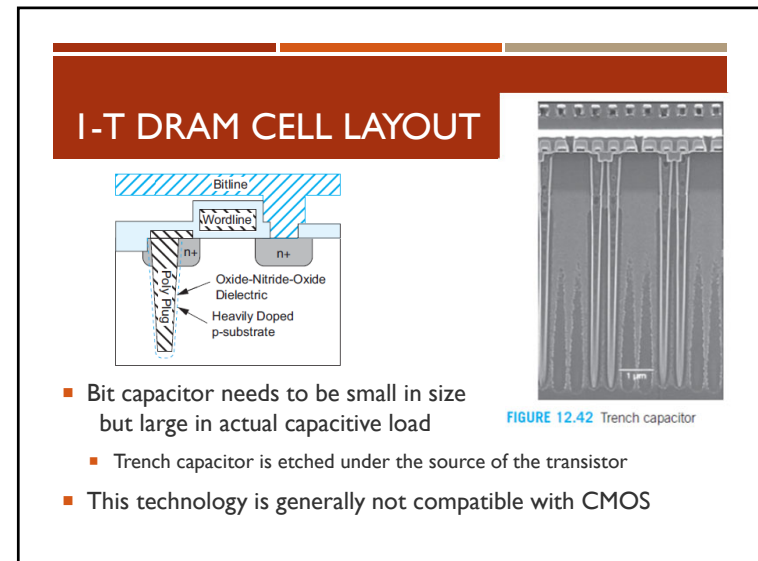
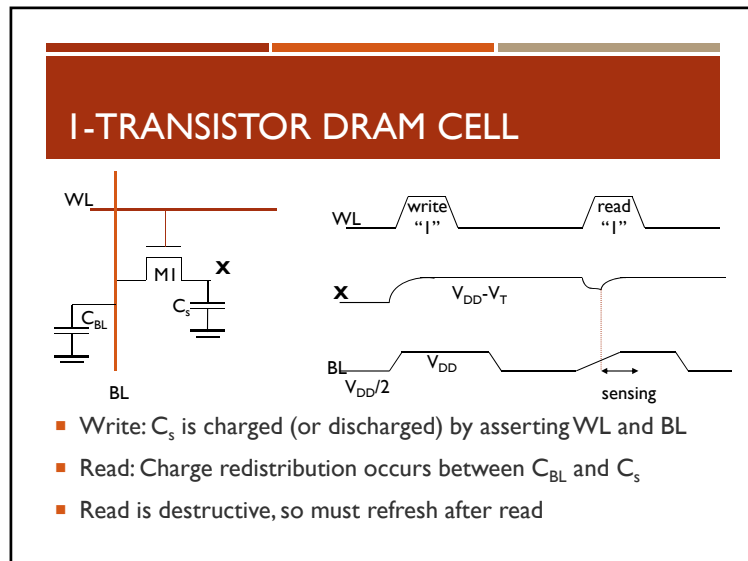
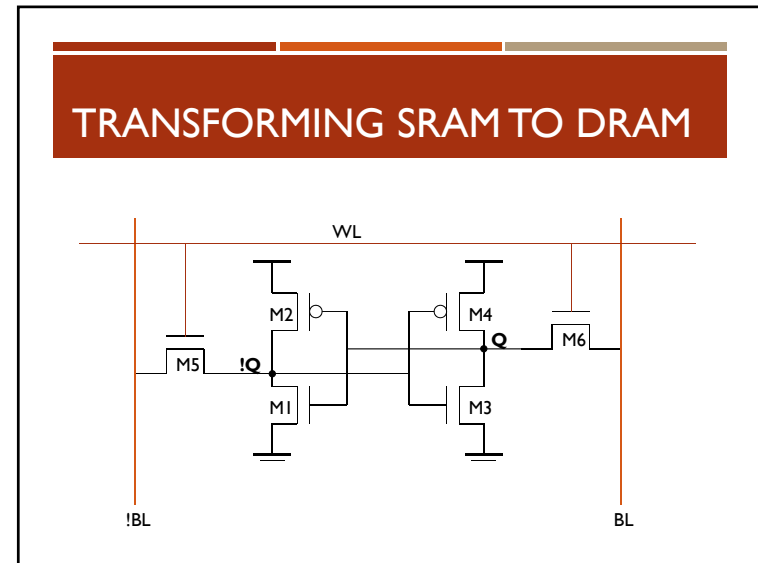
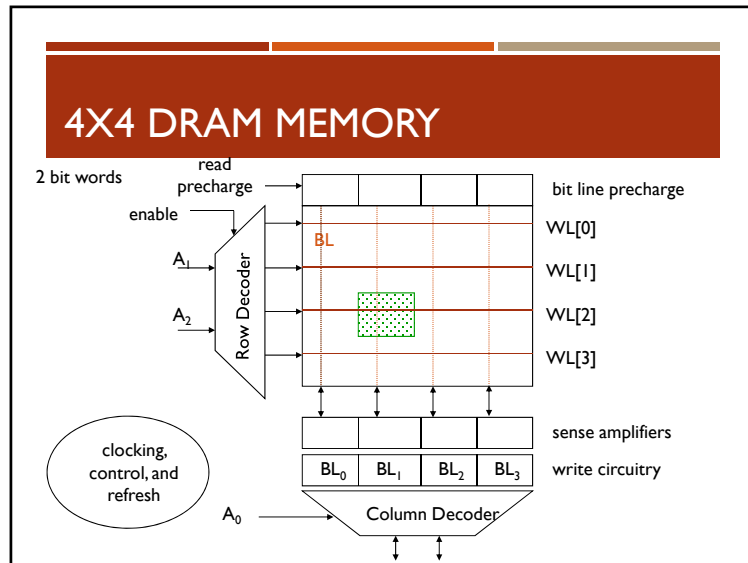
$$t_p = (C * \Delta V) / I_{av}$$

Annotations: C is large, ΔV is small, I_{av} is large. Note: make ΔV as small as possible.

- Power reduction: eliminates a large part of the power dissipation

$$P = \frac{1}{2} C * V_{DD} * \Delta V * f$$

Annotation: ΔV is small. Note: make ΔV as small as possible.



I-T DRAM CELL OBSERVATIONS

- Cell is single ended (complicates the design of the sense amp)
- Cell *requires* a sense amp for each bit line due to charge redistribution based read
 - all previous designs used SAs for speed, not functionality
- Cell read is destructive; refresh must follow to restore data
- Cell requires an extra capacitor (CS) that must be explicitly included in the design
 - not always compatible with logic CMOS process
- A threshold voltage is lost when writing a 1 (can be circumvented by bootstrapping the word lines to a higher value than VDD)